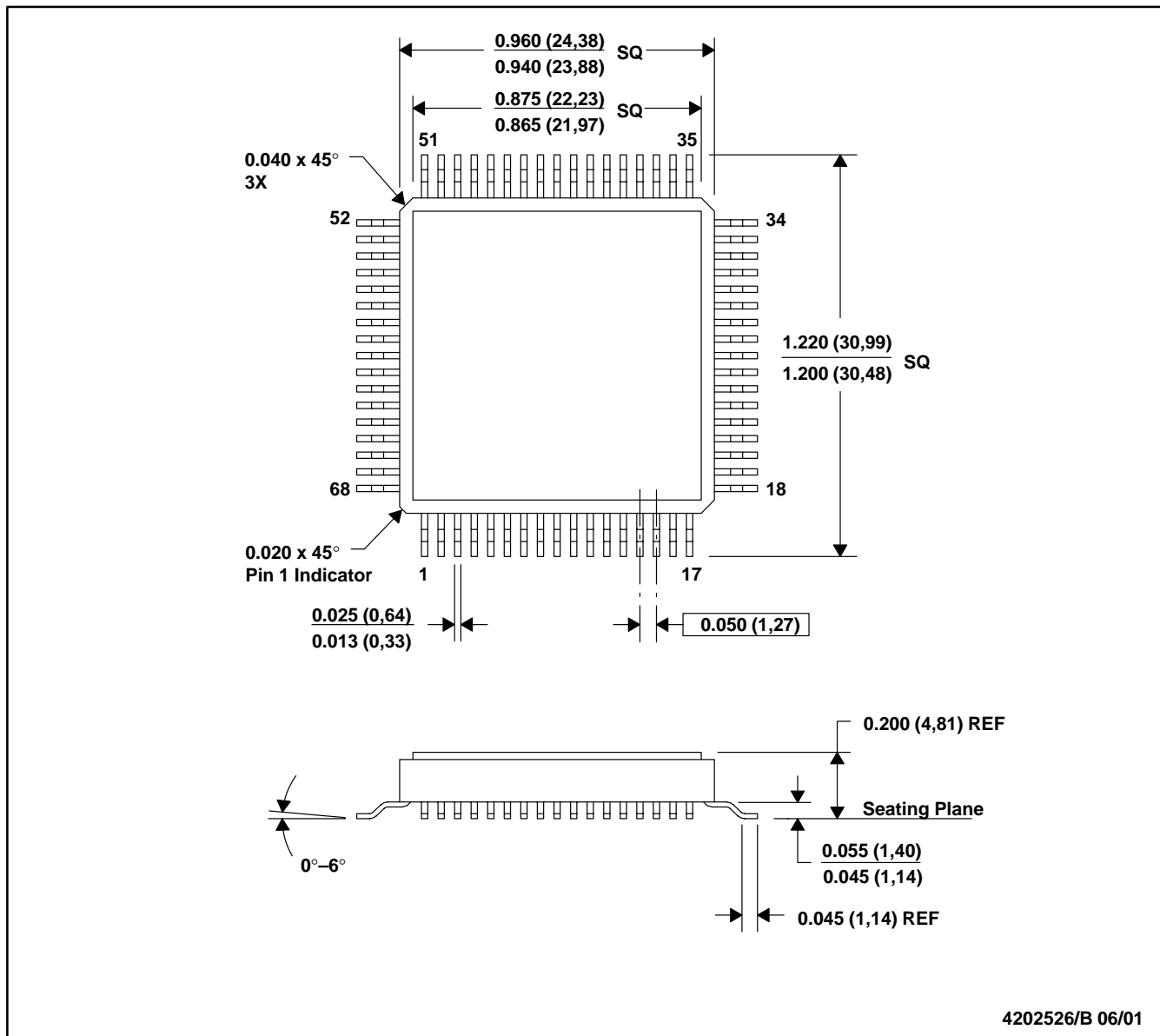


HBC (S-CQFP-L68)

CERAMIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Formed leads shall be planar with respect to one another within 0.004 (0,10) max at seating plane.

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